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# IDC10D120T6M

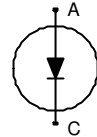
## Diode EMCON 4 Medium Power Chip

### FEATURES:

- 1200V EMCON 4 technology
- soft, fast switching
- low reverse recovery charge
- small temperature coefficient

### This chip is used for:

- low / medium power modules



### Applications:

- low / medium power drives

Chip Type	V <sub>R</sub>	I <sub>F</sub>	Die Size	Package
IDC10D120T6M	1200V	15A	3.30 x 2.98 mm <sup>2</sup>	sawn on foil

### MECHANICAL PARAMETER:

Raster size	3.30 x 2.98	mm <sup>2</sup>
Area total / active	9.83 / 5.33	
Anode pad size	2.346 x 2.026	
Thickness	110	μm
Wafer size	150	mm
Flat position	180	deg
Max. possible chips per wafer	1531 pcs	
Passivation frontside	Photoimide	
Pad metall	3200 nm AlSiCu	
Backside metall	Ni Ag –system suitable for epoxy and soft solder die bonding	
Die bond	electrically conductive glue or solder	
Wire bond	Al, ≤500μm	
Reject ink dot size	Ø 0.65mm; max 1.2mm	
Recommended storage environment	store in original container, in dry nitrogen, < 6 month at an ambient temperature of 23°C	



# IDC10D120T6M

## Maximum Ratings

Parameter	Symbol	Condition	Value	Unit
Repetitive peak reverse voltage	$V_{RRM}$		1200	V
Continuous forward current limited by $T_{jmax}$	$I_F$		1)	A
Maximum repetitive forward current limited by $T_{jmax}$	$I_{FRM}$		30	
Maximum junction and storage temperature	$T_{vj,max}$ , $T_{stg}$		-40...+175	°C
Reverse bias safe operating area <sup>2)</sup> (RBSOA)	$I_{F,max} = 30A$ , $V_{R,max} = 1200V$ , $T_{vj,op} \leq 150^\circ C$ , $P_{max} = \mathbf{tbd}$ kW			

1) depending on thermal properties of assembly

2) not subject to production test - verified by design/characterisation

## Static Electrical Characteristics (tested on wafer), $T_j=25^\circ C$

Parameter	Symbol	Conditions		Value			Unit
				min.	Typ.	max.	
Reverse leakage current	$I_R$	$V_R=1200V$	$T_j=25^\circ C$			3.5	$\mu A$
Cathode-Anode breakdown Voltage	$V_{Br}$	$I_R=0.25mA$	$T_j=25^\circ C$	1200			V
Forward voltage drop	$V_F$	$I_F=15A$	$T_j=25^\circ C$	1.35	1.7	2.05	V

## Dynamic Electrical Characteristics inductive load (not subject to production test - verified by design/characterization)

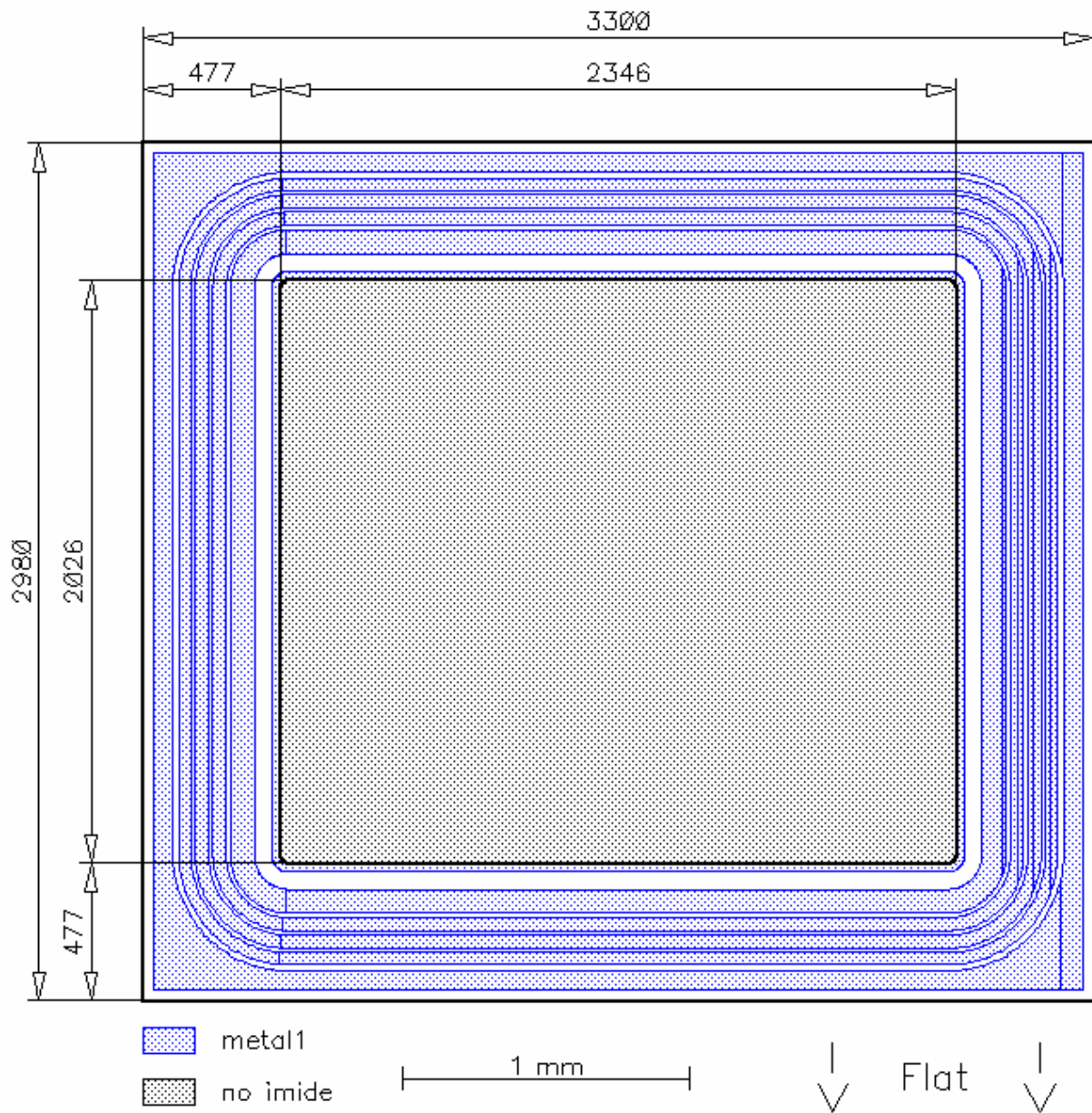
Parameter	Symbol	Conditions		Value <sup>2)</sup>			Unit
				min.	Typ.	max.	
Peak reverse recovery current	$I_{RM}$	$I_F=A$ $di/dt=A/\mu s$ $V_R=V$ $V_{GE}=-15V$	$T_j = 25^\circ C$ $T_j = 125^\circ C$ $T_j = 150^\circ C$		tbd		A
Reverse recovery charge	$Q_r$	$I_F=A$ $di/dt=A/\mu s$ $V_R=V$ $V_{GE}=-15V$	$T_j = 25^\circ C$ $T_j = 125^\circ C$ $T_j = 150^\circ C$		tbd		$\mu C$
Reverse recovery energy	$E_{rec}$	$I_F=A$ $di/dt=A/\mu s$ $V_R=V$ $V_{GE}=-15V$	$T_j = 25^\circ C$ $T_j = 125^\circ C$ $T_j = 150^\circ C$		tbd		mJ

2) values also influenced by parasitic L- and C- in measurement and package.

CHIP DRAWING:

## L4668B

Die-Size 3300 um x 2980 um





# IDC10D120T6M

## FURTHER ELECTRICAL CHARACTERISTICS:

This chip data sheet refers to the device data sheet

tbd

## Description:

AQL 0,65 for visual inspection according to failure catalog

Electrostatic Discharge Sensitive Device according to MIL-STD 883

Test-Normen Villach/Prüffeld

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